

**ABSTRACT OF THE DISCLOSURE**

The present invention discloses a white gold composition consisting essentially of copper, silver, zinc, and manganese, and further consisting of small amounts of tin, cobalt, silicon/copper and boron/copper. More particularly, the white gold composition of the present invention discloses a white gold composition consisting essentially of about 36% to about 57% copper, about 10% silver, about 18.2% to about 24.2% zinc, about 14% to about 28.9% manganese, and the balance further consisting of about 1% tin, about 0.025% to about 0.03% cobalt, about 0.52% silicon/copper, and about .2% boron/copper. An objective of the present invention is to provide for methods and compositions of casting, fabricating and soldering white gold that does not incorporate nickel or palladium. The present invention also discloses no tarnish results when hydrogen is used as a catalyst to all compositions.

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